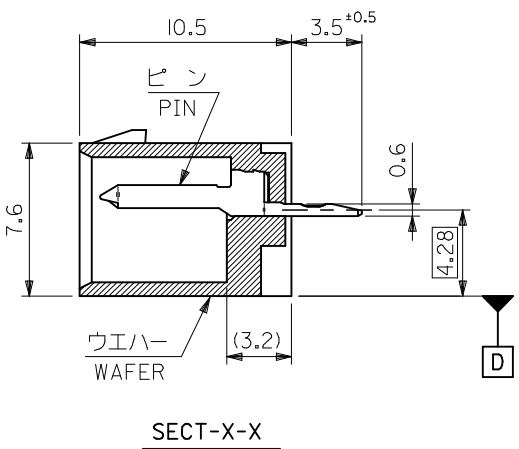
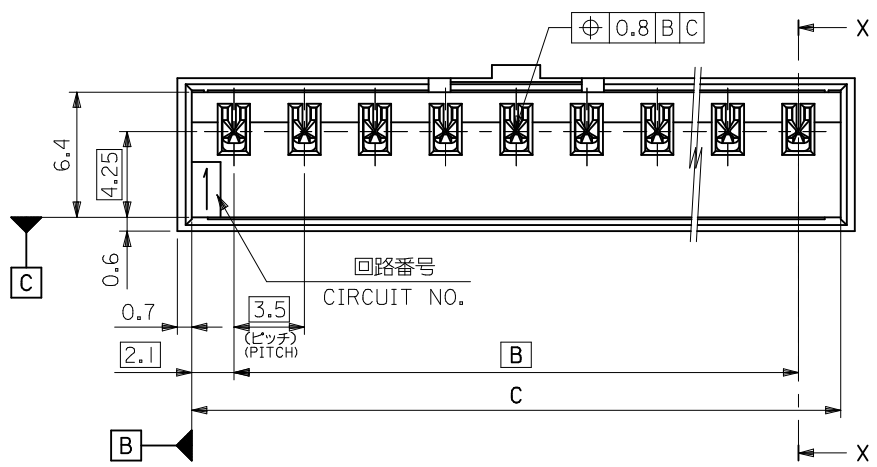


注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り) , UL94V-0
WAFER : PBTP (G.F 15%) , UL94V-0
ピン : 黄銅、ニッケル下地 鍍メッキ (t=0.254)
PIN : BRASS
TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53258-**-20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53258-**-20.
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 14μm MIN.
SURFACE PLATE : TIN 14μm MIN.
下地メッキ : ニッケルメッキ 14μm MIN.
UNDER PLATE : NICKEL 14μm MIN.

基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	53.2	49.0	54.6	53258-1529	15	
	49.7	45.5	51.1	-1429	14	
	46.2	42.0	47.6	-1329	13	
	42.7	38.5	44.1	-1229	12	
	39.2	35.0	40.6	-1129	11	
	35.7	31.5	37.1	-1029	10	
	32.2	28.0	33.6	-0929	9	
	28.7	24.5	30.1	-0829	8	
	25.2	21.0	26.6	-0729	7	
	21.7	17.5	23.1	-0629	6	
	18.2	14.0	19.6	-0529	5	
	8.7	14.7	10.5	16.1	-0429	4
	6.1	11.2	7.0	12.6	-0329	3
	6.1	7.7	3.5	9.1	53258-0229	2
(D)	C	B	A	MATERIAL NO.	CKT. 極致	

MATERIAL 材料
注記参照
SEE NOTES

REVISED EC NO: J2007-0432 DRW:KSAIT001 2006/08/11 CHKD:THARUYAMA 2006/08/21 APPR:NUKITA 2006/08/23	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. UENO	DATE 2004/04/22	TITLE 3.5 WIRE TO BOARD CONN -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/04/22	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/04/22	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53258-005	SHEET NO. 1 OF 1	
REV A	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					